Döcket No.: <u>LT-0050</u>

9404

As a below named inventor, I hereby declare that:

## **DECLARATION AND POWER OF ATTORNEY**

My residence, post office and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled\_DEVICE AND METHOD FOR MANAGING POWER IN COMPUTER SYSTEM, the specification of which

[X] is attached hereto	[] was filed on as amended on	Application Serial No(if applicable)	and was
I hereby state that I have r any amendment referred to	eviewed and understand the contents of the pabove.	e above identified specificati	ion, including the claims, as amended by
I acknowledge the duty to Federal Regulations, Section	disclose information which is known to me on 1.56(a).	to be material to patentabi	lity in accordance with Title 37, Code of
listed below and have also	iority benefits under 35 U.S.C. 119(a)-(d) y PCT international application which design identified below, by checking the box, any faving a filing date before that of the applications	mated at least one country of foreign application for paten	other than the United States of America,
Prior Foreign Applicatio	n(s):	Foreign Filing Date	e
Number	Country	Month/Day/Year	
10-2003-0036695	Republic of Korea	July 9, 2003	
I hereby claim the benefit	under 35 U.S.C. 119(e) of any United States	provisional application(s) li	sted below.

I hereby claim the benefit under 35 U.S.C. 120 of any United States application(s), or 365(c) of any PCT international application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of 35 U.S.C. 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

Filing Date (Month/Day/Year)

Prior U. S. Application or PCT Parent Number

Application Number(s):

Filing Date (Month/Day/Year)

Parent Patent Number (if applicable)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s):Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Carol L. Druzbick, Registration No. 40,287; Anthony H. Nourse, Registration No. 46,121; Laura L. Lee, Registration No. 48,752; Rene A. Vazquez, Registration No. 38,647; Donald R. McPhail, Registration No. 35,811; Timothy M. Speer, Registration No. 47,355; Ruay L. Ho, Registration No. 48,110; and Samuel W. Ntiros, Registration No. 39,318, all of

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